



Product Change Notification: MAAN-10SXHP968

Date:

15-Jun-2026

Product Category:

Depletion Mode Mosfets, N-Channel Enhancement Mode Mosfets, P-Channel Enhancement Mode Mosfets

Notification Subject:

CCB 8332 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Affected CPNs:

[MAAN-10SXHP968_Affected_CPN_06152026.pdf](#)

[MAAN-10SXHP968_Affected_CPN_06152026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
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Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 15, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MAAN-10SXHP968_Qualification_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

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Affected Catalog Part Numbers (CPN):

2N7002-G

DN1509T-V/C6X

DN3135K1-G

LND150K1-G

LND250K1-G

TN2106K1-G

TN2124K1-G

TN2124K1-G-D545

TN2130K1-G

TN5325K1-G

TN5335K1-G

TN5335K1-G-D589

TP0610T-G

TP2104K1-G

TP5322K1-G

TP5335K1-G

TP5335K1-G-AAA

TP5335K1-G-D588

VN2110K1-G

VP2110K1-G

VP2110K1-G-D537



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QUALIFICATION PLAN SUMMARY

PCN #: MAAN-10SXHP968

Date:

June 4, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

CCB No.: 8332

<u>Misc.</u>	Assembly site		MTAI
	BD Number		BD-004443-02
	MP Code (MPC)		6H002QC6XD00
	Part Number (CPN)		TP5335K1-G
	MSL information		MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)		T/R
	Base Quantity Multiple (BQM)		3000
	Reliability Site		MTAI
<u>Lead-Frame</u>	Paddle size		64x38 mils
	Material		CDA194
	DAP Surface Prep		Ag Spot Plating
	Treatment		None
	Process		Stamped
	Part Number		10100301
	Lead Plating		Matte Tin
	Strip Size		228.288x50.800mm
	Strip Density		256units/strip
<u>Bond Wire</u>	Material		CuPdAu
<u>Die Attach</u>	Part Number		8060T (PFAS-free)
	Conductive		Yes
	<u>Backside Coat</u> (If Applicable)	Material	Au
		Thickness	~0.4um
		Conductive	Yes
<u>MC</u>	Part Number		G600V
<u>PKG</u>	Package Type		SOT-23
	Pin/Ball Count		3
	PKG width/size		1.3mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5		MTAI	SOT-23	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5		MTAI	SOT-23	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5		MTAI	SOT-23	
HTSL (High Temp Storage Life)	JESD22-A103. +175°C for 504 hours or +150°C for 1008 hrs. Electrical test pre and post stress at +25°C and +150°C hot temp.	45	5	3	150	0	10	MTAI	MTAI	SOT-23	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1/260C	231	15	3	738	0	15	MTAI	MTAI	SOT-23	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C and +150°C hot temp.	77	5	3	246	0	10	MTAI	MTAI	SOT-23	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	SOT-23	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at +150°C hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	SOT-23	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.